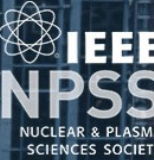


# 2023 IEEE Nuclear Science Symposium, Medical Imaging Conference and Room Temperature Semiconductor Detector Conference

4 - 11 November, 2023, Vancouver, Canada



## ePixHRM320k A Detector System for Soft X-ray Imaging for LCLS-II

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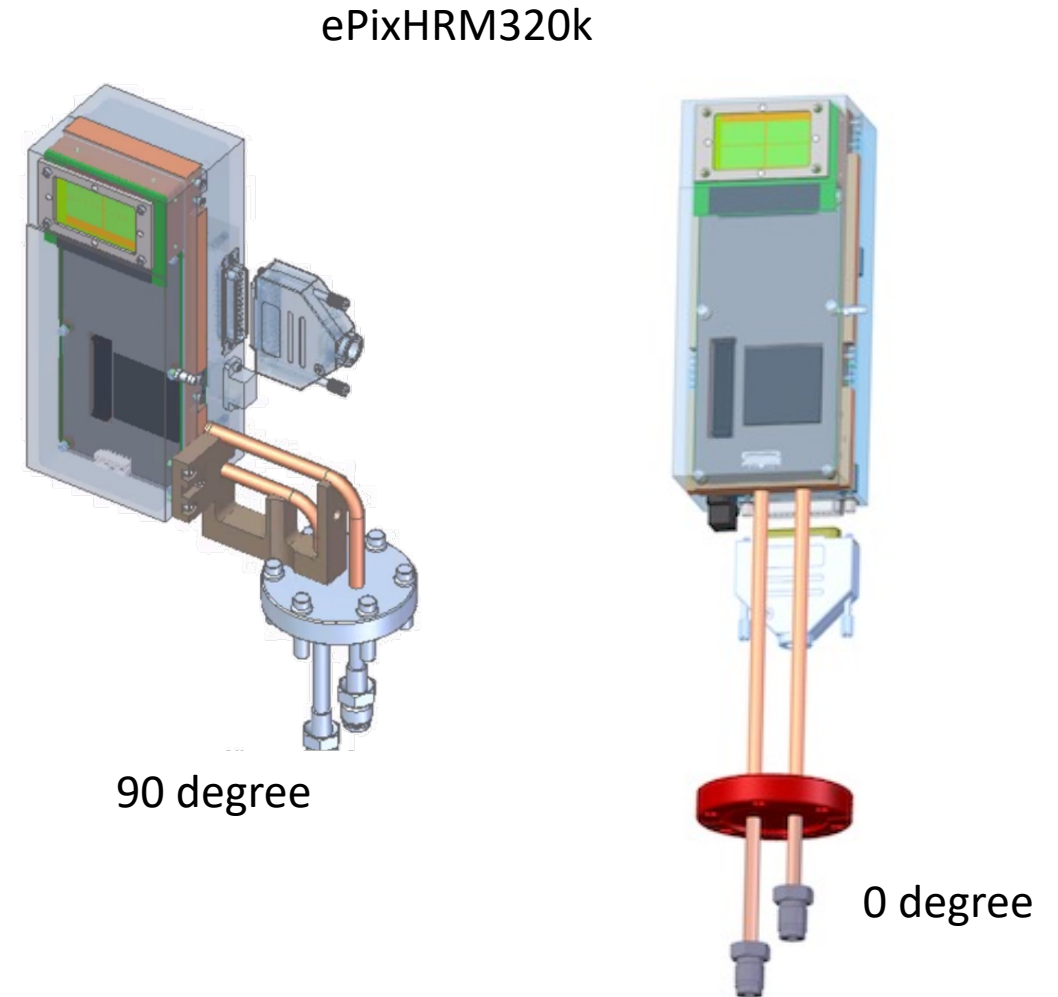
Dionisio Doering, Lorenzo Rota, Aldo P. Perez, Bojan Markovic, Aseem Gupta, Dawood Alnajjar, Larry Ruckman, Donald Geranen, Marco Oriunno, Conny Hasson, Julie Segal, Christopher Kenney and Angelo Dragone

SLAC X-ray Detector R&D Program

# Outline

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- Project goals
- Project requirements
- Detector concept
- Status of the demonstrator:
  - Pixel performance and new fabrication run
  - Back-end ASIC performance
  - Assembled modules



# Project Goal

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- ePixM project aims at developing a high-rate camera for soft X-rays scattering/imaging experiments at LCLS-II
- Key detector for NEH 2.2 beamline:
  - QRIXS Instrument
    - Soft x-ray (SXR) resonant elastic X-ray scattering (REXS) experiments
    - X-ray Photon Correlation Spectroscopy (XPCS)
  - ChemRIXS Instrument
  - Other Coherent Scattering (CS) experiments

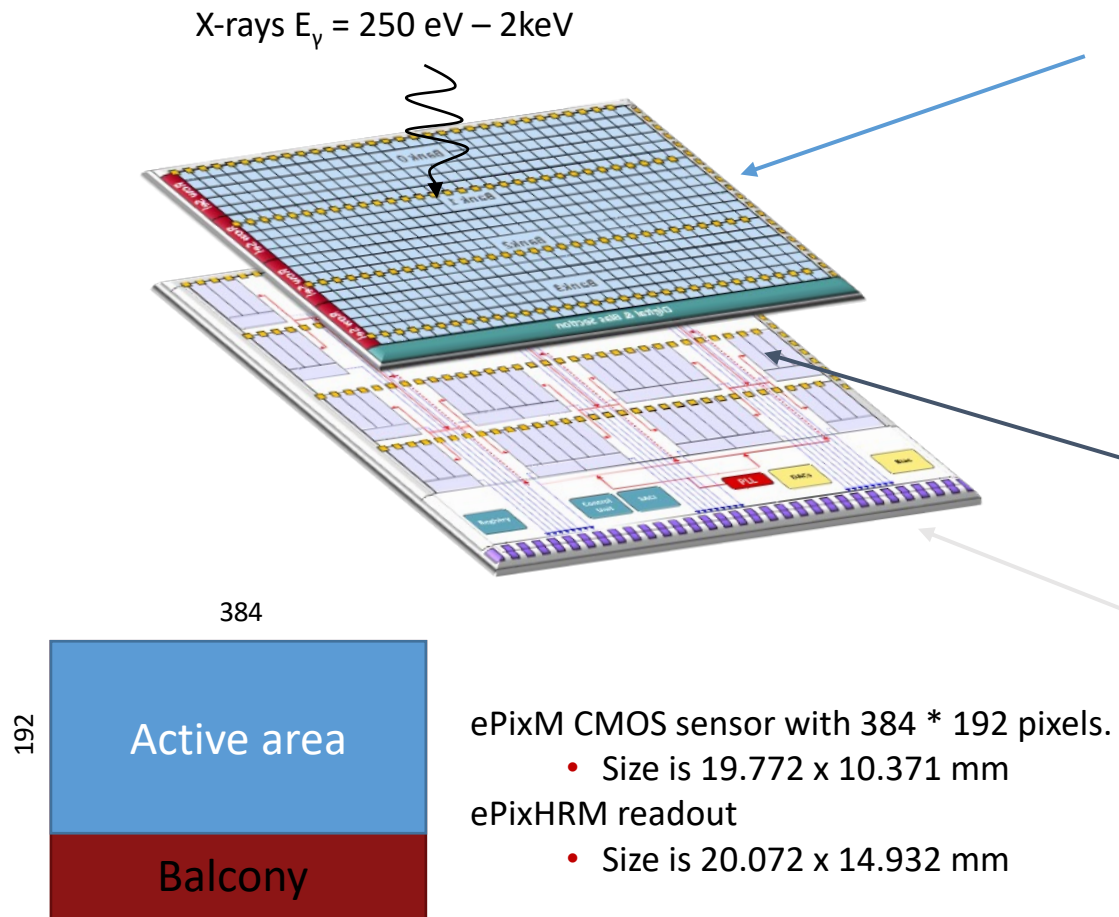
# Project requirements

Parameter	Threshold	Goal	REXS	XPCS	CS	0.3 Mpix ePixM
Pixel pitch [ $\mu\text{m}$ ]	50	50	✓	✓	✓	50
Read noise [ $e^-$ rms]	15	10		✓	✓	12
Well depth [Number of 530eV photons]	1000	3000	✓	✓	✓	>1000
Quantum efficiency [% , 275eV-1500eV]	70	90	✓	✓	✓	~84
Frame-rate [kHz]	5	10	✓	✓	✓	7.5
Array size [pixels]	512x512	1024x1024	✓		✓	768 * 384
Vacuum outgassing rate [torr*L/s]	2E-8	1E-8	✓			2E-8
Cabling and cooling length [m]	2	4	✓		✓	2
Physical package envelope [WxLxD]	100x175x75 mm	75x150x50 mm	✓			75x175x58 mm
Maximum power dissipation [W]	100*	50	✓	✓	✓	75

\* Assuming a 512x512

# Detector Concept

## Standard modular hybrid approach



### ePixM Monolithic Active Pixel Sensor (MAPS)

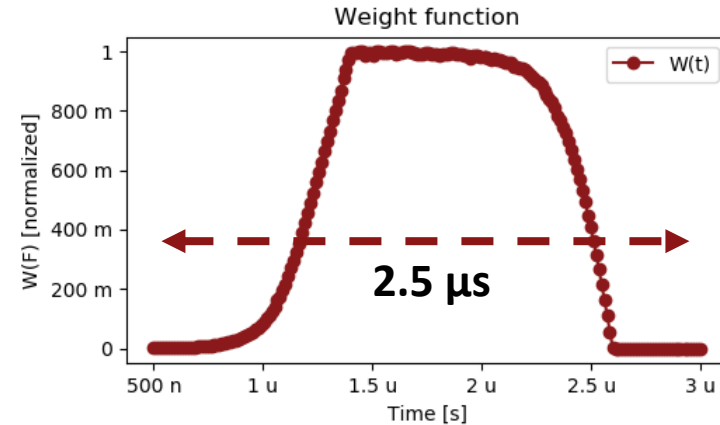
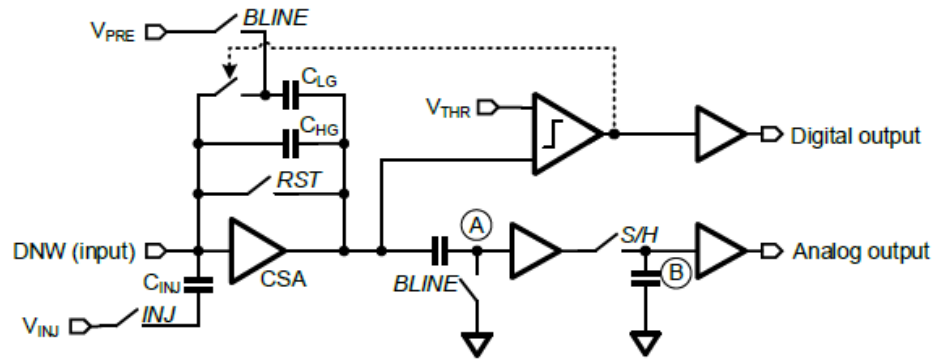
- On-sensors amplifier reduces noise
- Fully-depleted and back-illuminated
- Entrance window optimized for soft X-rays

### Standard micro-bumps

### ePixHR-M Readout ASIC (ROIC)

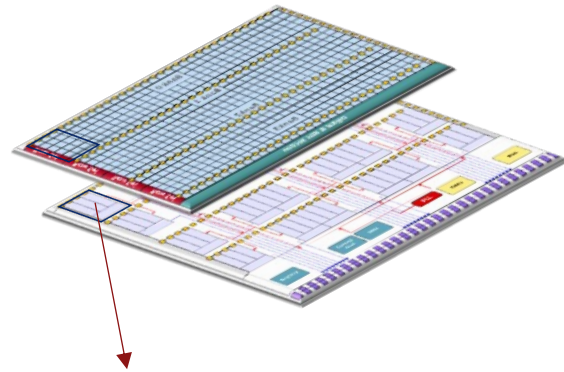
- 4 arrays of 192 ADCs

# ePixM: pixel electronics

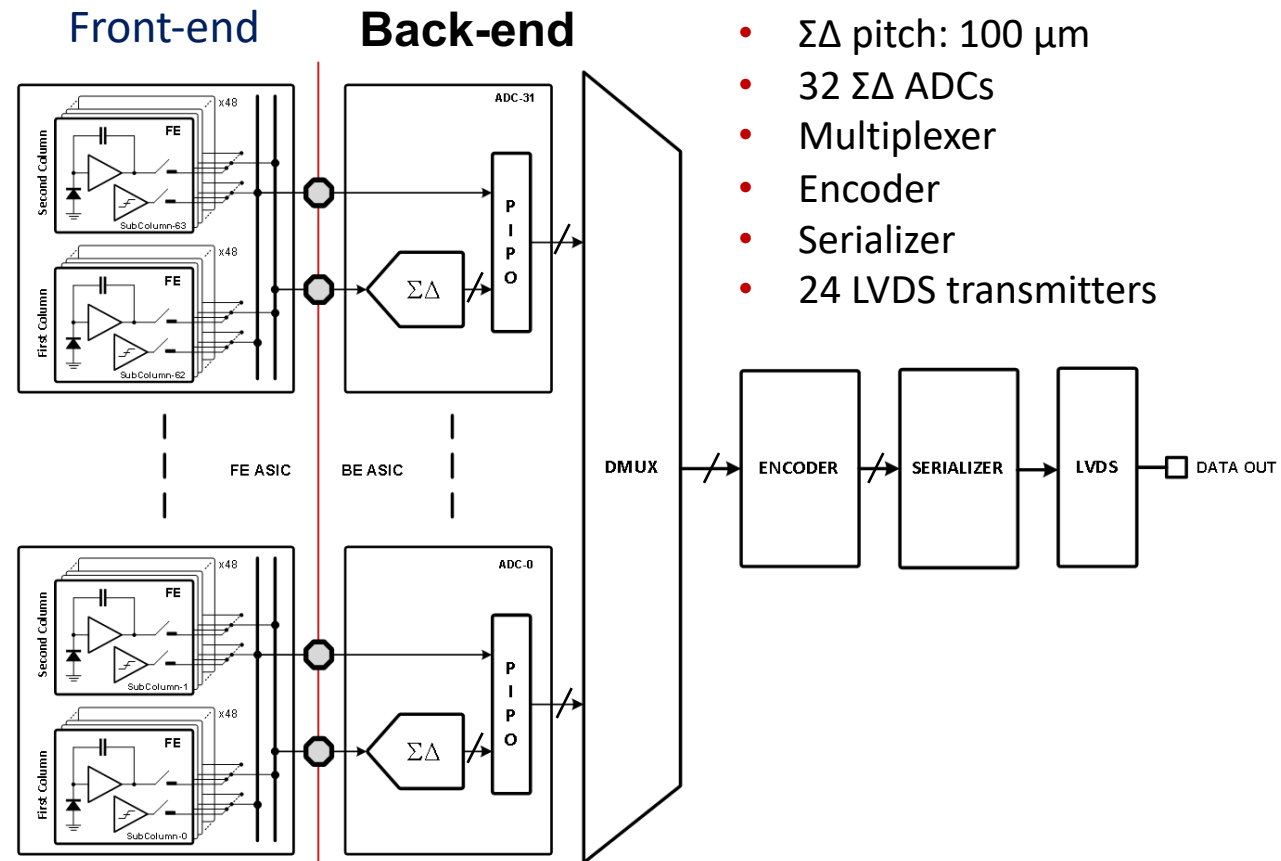


- Charge Sensitive Amplifier (CSA) with auto-ranging capability
- Injection capacitance for calibration
- Correlated Double Sampling (CDS) → quasi-trapezoidal shaping
- Sampling stage and 2x column buffers for analog and comparator (gain) output

# ePixM interface between CMOS sensor and ROIC



- Pixel pitch: 50  $\mu\text{m}$
- Subgroup of 48 x 2 pixels



# Requirements table

Parameter	Threshold	Goal	REXS	XPCS	CS	0.3 Mpix ePixM
Pixel pitch [ $\mu\text{m}$ ]	50	50	✓	✓	✓	50
Read noise [ $e^-$ rms]	15	10		✓	✓	12
Well depth [Number of 530eV photons]	1000	3000	✓	✓	✓	>1000
Quantum efficiency [% , 275eV-1500eV]	70	90	✓	✓	✓	~84
Frame-rate [kHz]	5	10	✓	✓	✓	7.5
Array size [pixels]	512x512	1024x1024	✓		✓	768 * 384
Vacuum outgassing rate [torr*L/s]	2E-8	1E-8	✓			2E-8
Cabling and cooling length [m]	2	4	✓		✓	2
Physical package envelope [WxLxD]	100x175x75 mm	75x150x50 mm	✓			75x175x58 mm
Maximum power dissipation [W]	100*	50	✓	✓	✓	75

\* Assuming a 512x512

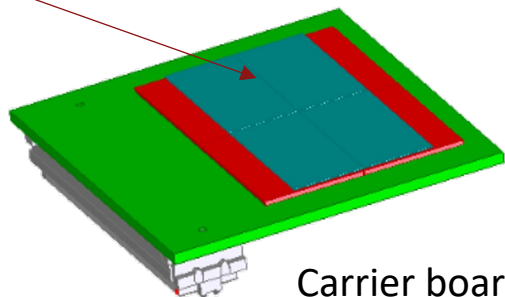


# System structure

- Carrier board
  - Focal plane with 4 ASICS
- Digital board
  - FPGA and voltage regulators for the ASICS
- Power and communication board
  - Input power at 24V gets reduced and distributed at 6V
  - LeapOn Transceiver implements 12 lanes of fiber optics communication

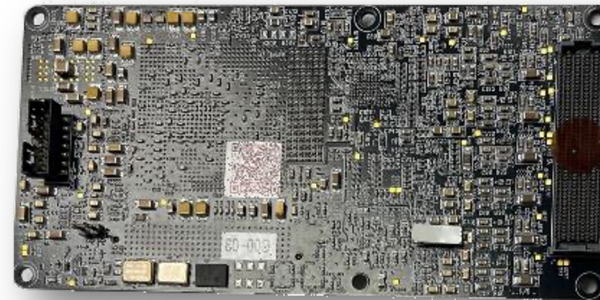
	Balcony	Balcony	
192	Active area	Active area	
192	Active area	Active area	
	Balcony	Balcony	
	384	384	

Read out ASIC  
& Sensor



Carrier board

Digital Board



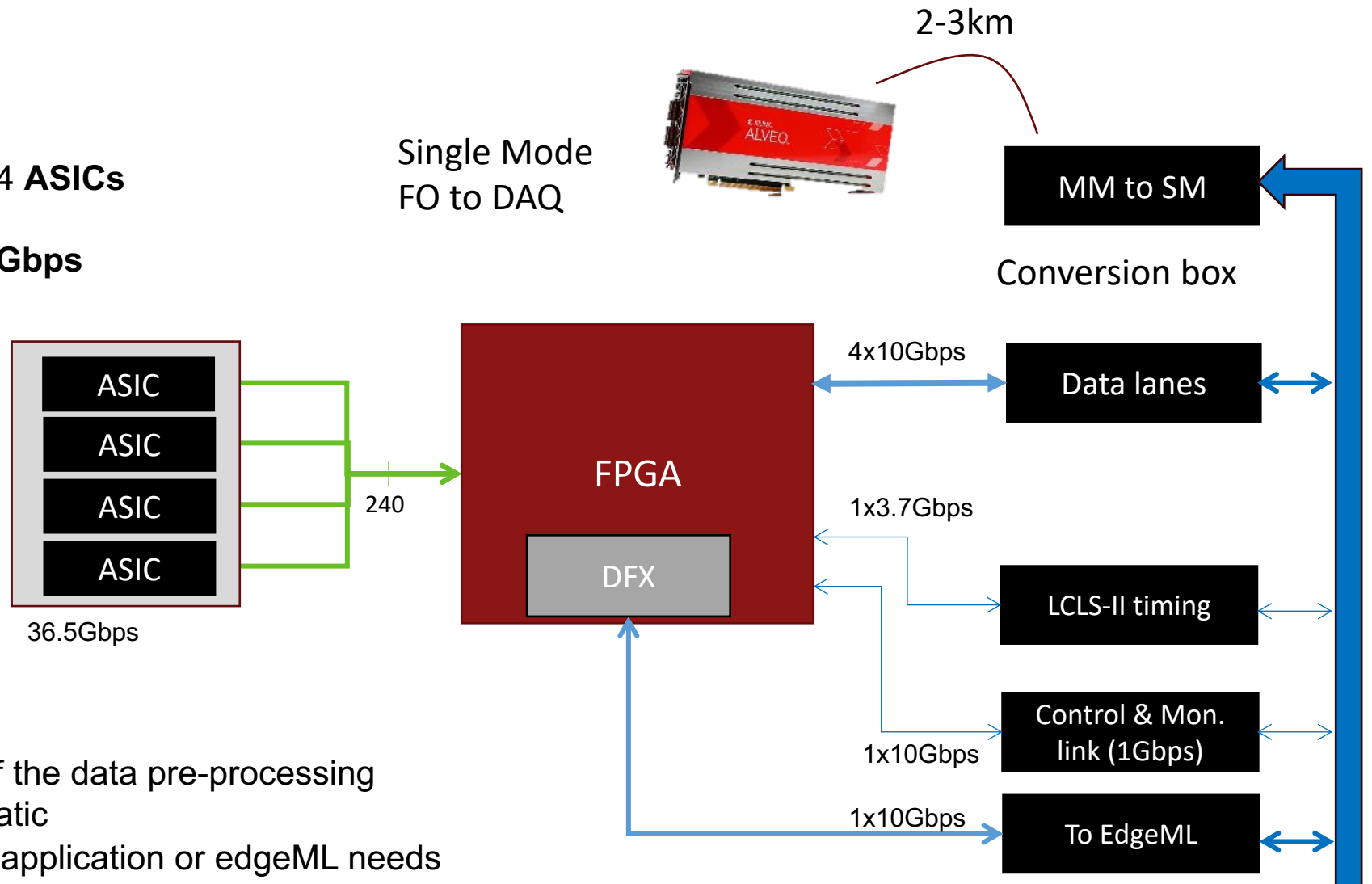
Carrier board



Power and communication

# Camera data flow

- ePixM 7.5 kfps data rate
  - 384\*192 pixels \* 16 bits \* 4 ASICs
  - \*7500 frames per second
  - \*66/64 encoding => 36.5-Gbps



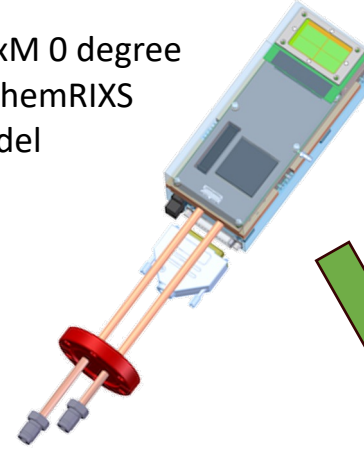
## DFX

- Enables dynamic optimization of the data pre-processing
- Image acquisition and control static
- Can be tailored for custom user application or edgeML needs

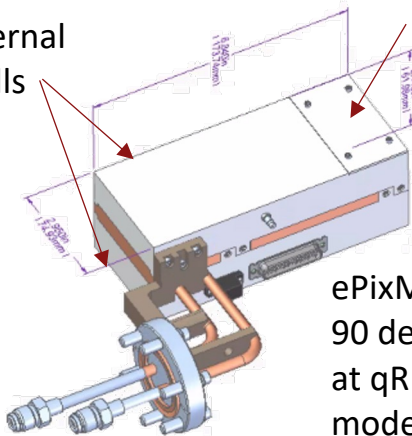
# Mechanical concept

- Overall dimensions: 75x175mmx58
- Side entrance window with Shield
- Cooling lines, one inlet and one outlet
- Vacuum requirements implemented with no water to vacuum joints

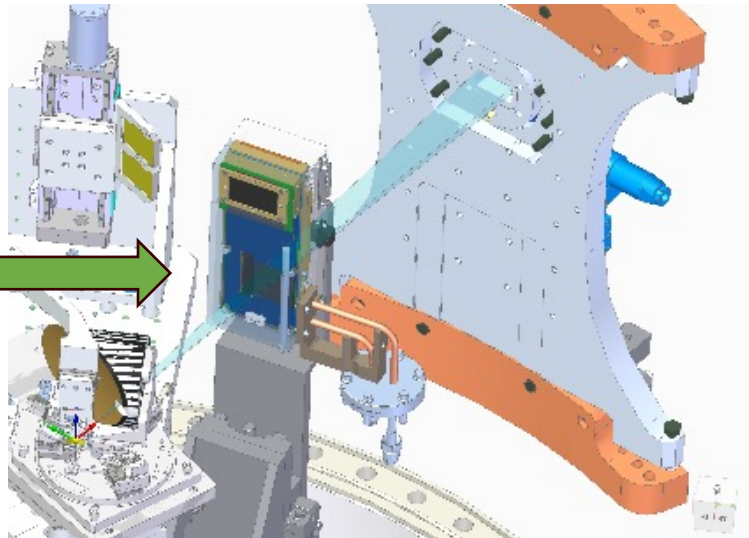
ePixM 0 degree  
at chemRIXS  
model



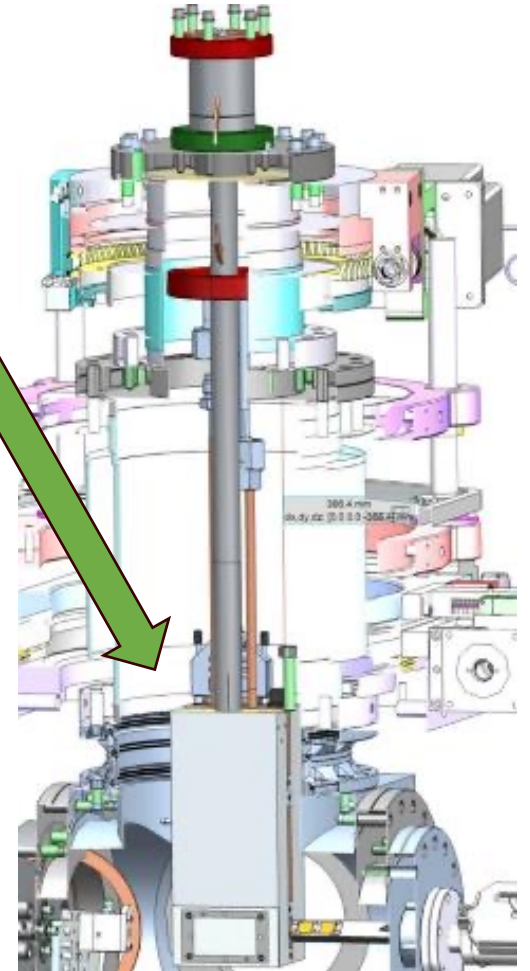
External shells  
Protection cover



ePixM  
90 degree  
at qRIXS  
model



ePixM 90 degree at qRIXS exp. chamber



# Test results with full system

- System level functionality
  - ADC test using external DAC, Supply for four ASIC, Timing to the detector
- ASIC level functionalities
  - Noise, X-Ray with  $\text{Cd}^{109}$ , Spatial data descrambling, Pixel gain

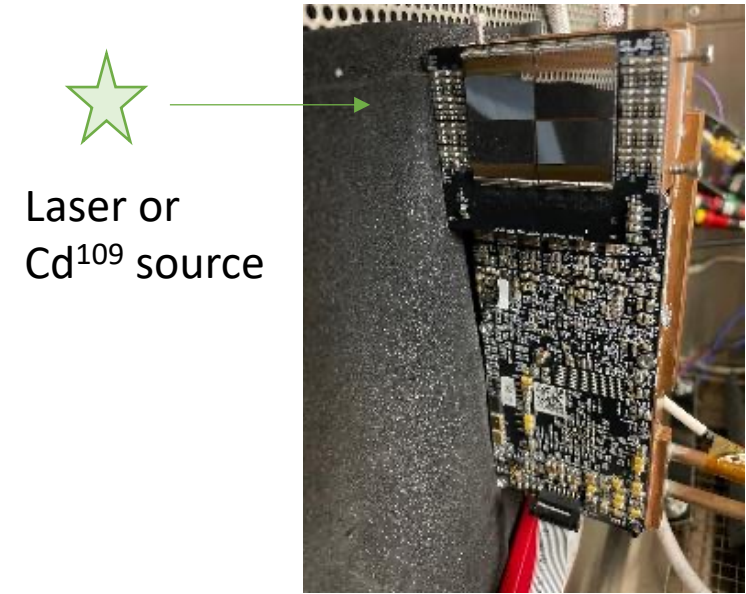
## Note on sensor:

### Batch IZM-0

- 700 micron thick sensor wafer – no entrance window – lowest risk
- Results presented today

### Batch IZM-1

- First science modules
- SLAC will thin, polish, implant, metalize, anneal sensor wafers
- Sent to IZM by Q2 CY2023 and receive Q4 CY2023



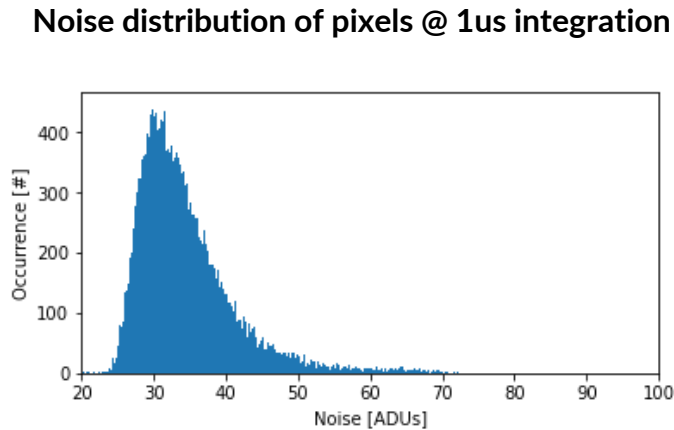
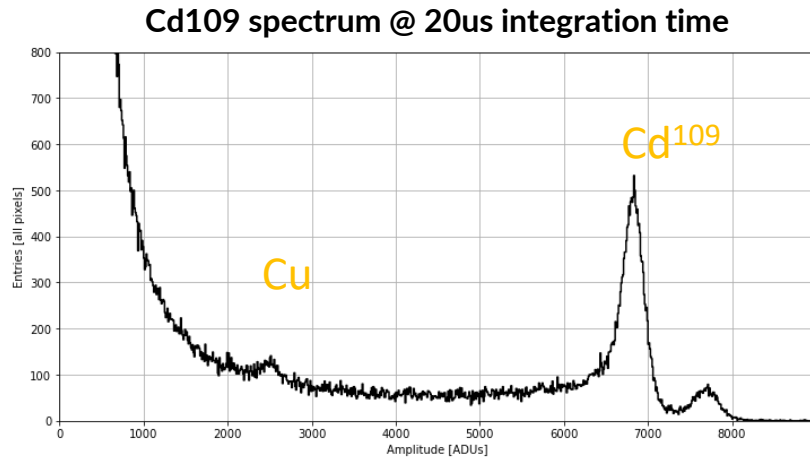
Laser or  $\text{Cd}^{109}$  source

Prototype Detector

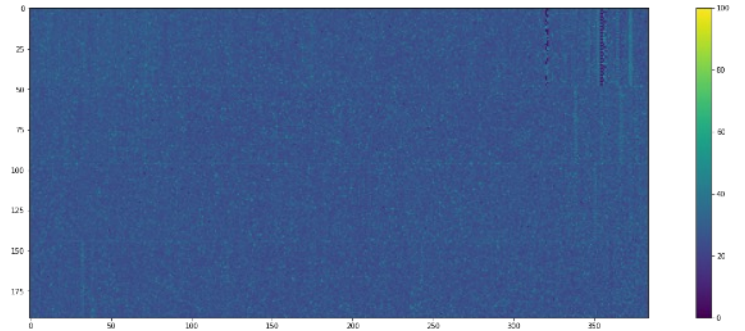


LASER pointer projected image

# Testing with Cd109 source



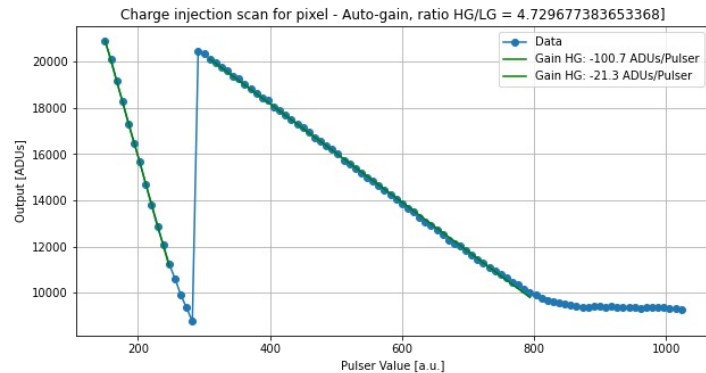
Noise map of 192x384 pixel array



- Thick sensor wafer (700um thickness, back-side not processed, not implanted/annealed)
- Sensor operating conditions: bias voltage =71V, leakage current 350 nA / ASIC (not processed!)
- 700um thick sensor noise performance, not fully depleted and not annealed: **28 e<sup>-</sup>**
- Final sensor expected to have performance in line with the small prototypes
- Preliminary data processing:
  - Pedestal subtraction
  - Common-mode noise correction (8% improvement at low-occupancy)

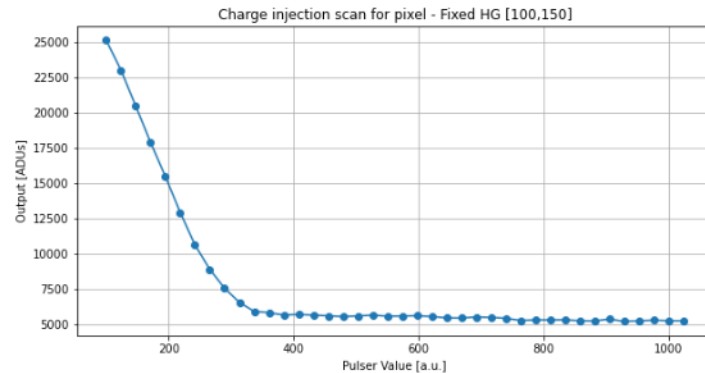
# Pixel – different gain modes

- Due to area/noise constraints, the pixels do not contain registers which configure the functionality of the pixels.
- Pixel can be configured to run in different gain modes by adjusting comparator threshold



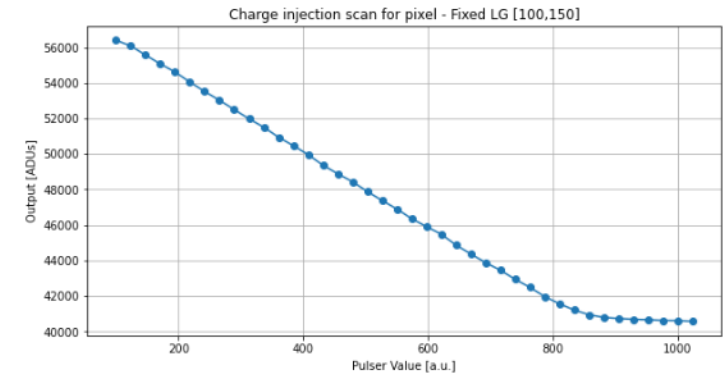
Auto-gain switching

Comparator in the high gain range



Fixed high-gain

Comparator maxed out



Fixed low-gain

Comparator at minimum level

# Summary & Next steps

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## ePixM sensor, ePixHRM readout ASIC and detector

- The updates on the development of the sensor and ASIC module has been presented
- The integration of the detector into two experimental chambers has been presented
- Initial performance measurements with thick sensor has been demonstrated
- Next steps
  - DAQ integration
  - Assembly of thin sensor into a detector
  - Tests with LCLS super conducting linear accelerator beam